

PETITIONER'S EXHIBIT LIST

Exhibit	Description
1001	U.S. Patent No. 7,256,486 (“486 patent”)
1002	Prosecution History of U.S. Patent No. 7,256,486 (“Prosecution History”)
1003	Declaration of Michael Pecht, Ph.D. (“Pecht”)
1004	Modern Dictionary of Electronics (7th ed. 1999) pg. 239 and 467
1005	Microchip Fabrication (4th ed. 2000) pg. 396
1006	Pecht <i>et al.</i> “Plastic Encapsulated Microelectronics” (1995) pg. 459
1007	Meriam Webster’s Collegiate Dictionary (10th ed. 1997) pg. 730
1008	Japanese Patent Application Publication No. 2003-17754, English translation of Japanese Patent Application Publication No. 2003-17754 and Translator Declaration (Rohm)
1009	Japanese Patent Application Publication No. 2001-352102 English translation of Japanese Patent Application Publication No. 2001-352102 and Translator Declaration (Matsushita)
1010	U.S. Patent No. 5,376,580 (“Kish”)
1011	U.S. Patent No. 5,523,589 (“Edmond 589”)
1012	U.S. Patent No. 6,791,119 (“Slater”)
1013	U.S. Patent No. 5,416,342 (“Edmond 342”)
1014	CV of Pecht
1015	Pecht, M., R. Agarwal, P. McCluskey, T. Dishongh, S. Javadpour, and R. Mahajan, <i>Electronic Packaging Materials and their Properties</i> , CRC Press, Boca Raton, FL, 1999 pg. 37 (“Electronic Packaging”)
1016	Infringement Contentions for Patent U.S. Patent No. 7,256,486 in Case No. 8:17-cv-00981-JVS-JCG in CDCA